

PNA1803L

Silicon planar type

For optical control systems

■ Features

- Fast response
- Wide spectral sensitivity characteristics
- $\phi 3$ plastic package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Emitter-collector voltage (Base open)	V_{ECO}	5	V
Collector current	I_{C}	20	mA
Collector power dissipation *	P_{C}	50	mW
Operating ambient temperature	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +100	$^\circ\text{C}$

■ Electrical-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Photocurrent *1	I_{L}	$V_{\text{CE}} = 10 \text{ V}, L = 1000 \text{ lx}$	1.0		3.0	mA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{\text{CE}} = 10 \text{ V}$		1	500	nA
Peak sensitivity wavelength	λ_{PD}	$V_{\text{CE}} = 10 \text{ V}$		800		nm
Half-power angle	θ	The angle when the photocurrent is halved		30		$^\circ$
Rise time *2	t_{r}	$V_{\text{CC}} = 10 \text{ V}, I_{\text{L}} = 1 \text{ mA}, R_{\text{L}} = 100 \Omega$		2.5		μs
Fall time *2	t_{f}			3.5		μs

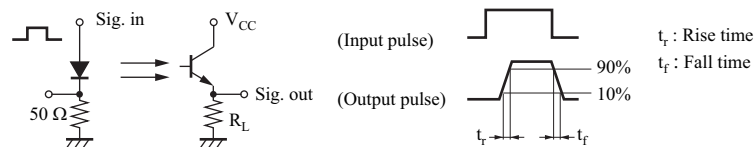
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.

3. This device is designed by disregarding radiation.

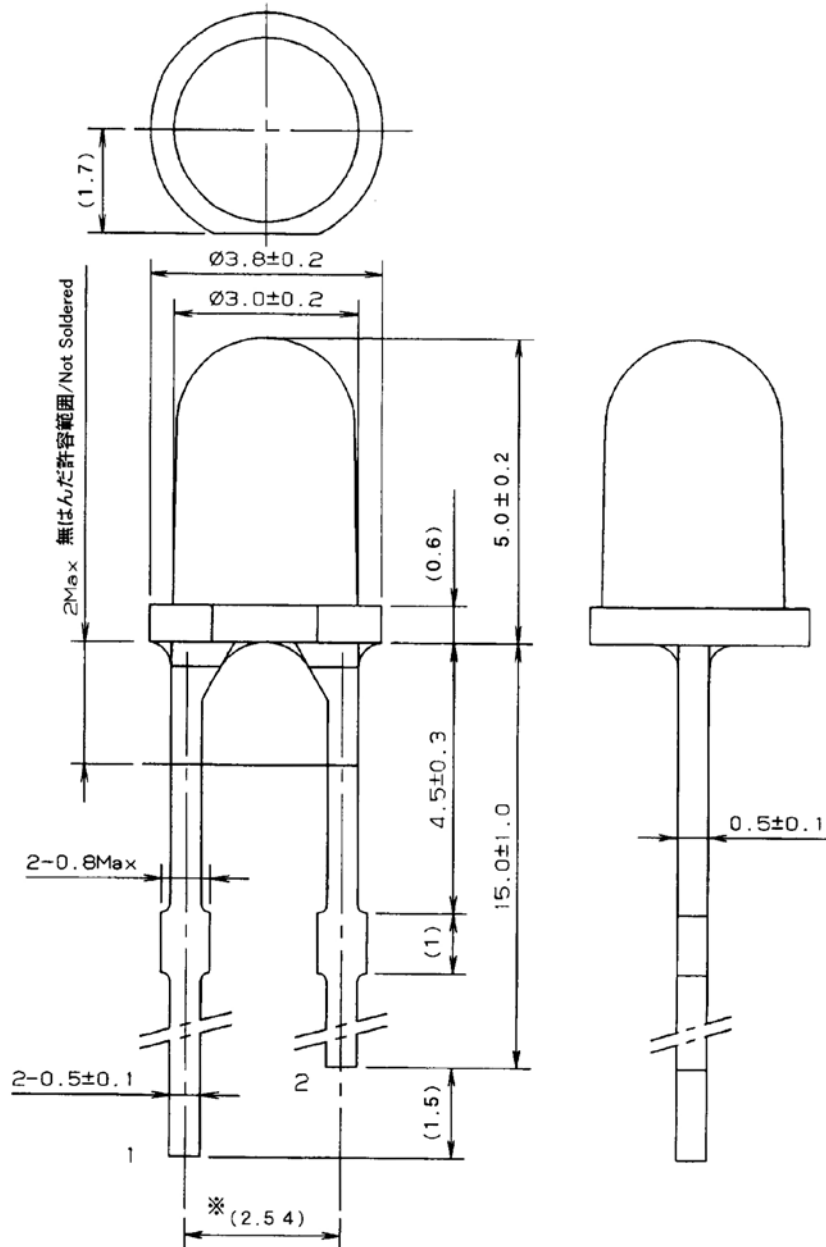
4. *1:Source: Tungsten lamp (color temperature 2 856K)

*2: Switching time measurement circuit



■ Package (Unit: mm)

LPXLTN2S0002



● Pin name

1: Emitter

2: Collector

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